



Material Content Data Sheet



Sales Product Name		IFX25401TBV		Issued		18. August 2015		
MA#		MA001380412						
Package		PG-TO263-5-1		Weight*		1673.87 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.179	0.19	0.19	1899	1899
leadframe	non noble metal	iron	7439-89-6	0.483	0.03		288	
	inorganic material	phosphorus	7723-14-0	0.145	0.01		87	
	non noble metal	copper	7440-50-8	482.096	28.80	28.84	288015	288390
wire	non noble metal	aluminium	7429-90-5	0.277	0.02	0.02	165	165
encapsulation	organic material	carbon black	1333-86-4	1.456	0.09		870	
	plastics	epoxy resin	-	66.987	4.00		40020	
	inorganic material	silicondioxide	60676-86-0	659.678	39.40	43.49	394103	434994
leadfinish	non noble metal	tin	7440-31-5	12.524	0.75	0.75	7482	7482
plating	non noble metal	nickel	7440-02-0	0.243	0.01		145	
	inorganic material	phosphorus	7723-14-0	0.001	0.00	0.01	1	145
solder	noble metal	silver	7440-22-4	0.119	0.01		71	
	non noble metal	tin	7440-31-5	0.095	0.01		57	
	non noble metal	lead	7439-92-1	4.552	0.27	0.29	2719	2847
heatspreader	non noble metal	iron	7439-89-6	0.442	0.03		264	
	inorganic material	phosphorus	7723-14-0	0.133	0.01		79	
	non noble metal	copper	7440-50-8	441.456	26.37	26.41	263735	264078
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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